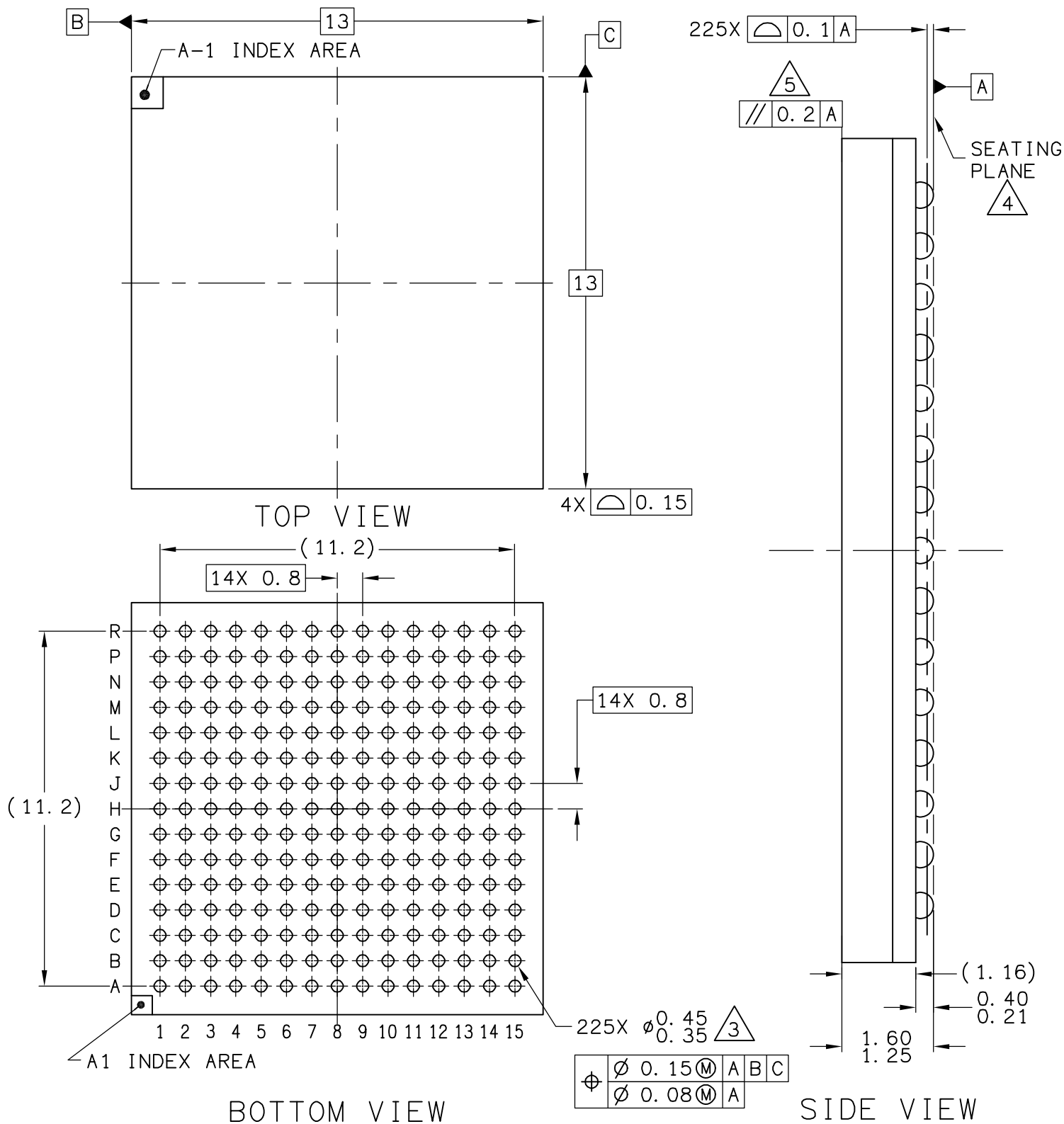




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TITLE: 225 I/O, LOW PROFILE, FINE PITCH, PBGA, 13 X 13 PKG, 0.8MM PITCH (STD. MAP)			DOCUMENT NO: 98ASA99207D		REV: A
			CASE NUMBER: 1304B-01		27 JUL 2005
			STANDARD: NON-JEDEC		

NOTES:

- 1. ALL DIMENSIONS IN MILLIMETERS.
- 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
- 3. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM A.
- 4. DATUM A, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- 5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

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